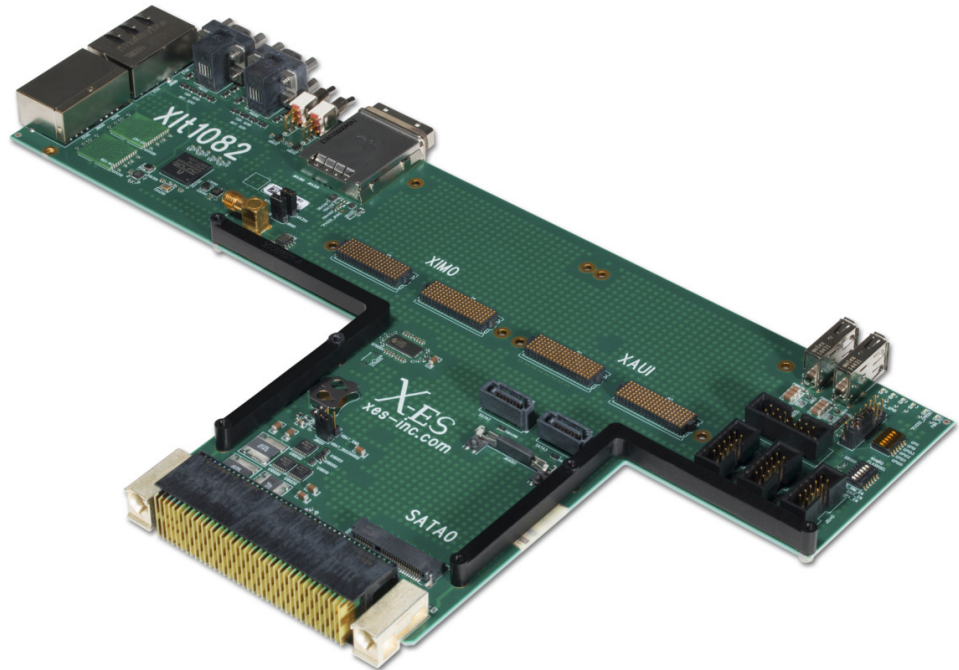


XIt1082

End of Life3U VPX Rear Transition Module with Gigabit Ethernet, SATA, USB, Serial, and 10GBASE-T **Please see XIt1086**

- ▶ 3U VPX Rear Transition Module (RTM)
- ▶ Four 10/100/1000BASE-T Ethernet ports
- ▶ Two 10GBASE-T Ethernet ports via dataplane breakout modules
- ▶ Four RS-232/422/485 serial ports
- ▶ Two USB 2.0 ports
- ▶ Four SATA ports (two via mSATA connectors)
- ▶ One XIM site



XIt1082

The XIt1082 is a 3U VPX Rear Transition Module (RTM), which supports I/O breakout from select X-ES Intel® Xeon® D 3U VPX SBCs. When installed in an RTM slot of an appropriate 3U VPX backplane, the XIt1082 routes I/O signals from an associated SBC's rear panel P0-P2 connectors through the VPX backplane to connectors on the XIt1082 to allow connection of these signals to external equipment. The XIt1082 routes four 10/100/1000BASE-T Ethernet ports to RJ-45 connectors, four RS-232/422/485 ports to micro-DB-9 connectors, two USB 2.0 ports to USB Type A connectors, and four SATA ports (two via mSATA connectors). A XIM site is also provided for breakout of the mezzanine's P16 I/O to the XIt1082's front panel via the appropriate XIM.

One dataplane breakout site connects two x4 Fat Pipes from the P1 and P2 connector to breakout modules that convert the signals to standard connectors. This facilitates rapid prototyping of complex system topologies using standard, off-the-shelf equipment.

X-ES

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Ethernet

- Four 10/100/1000BASE-T Ethernet ports to RJ-45 connectors

Serial

- Four RS-232/422/485 ports to micro-DB-9 connectors

USB

- Two USB 2.0 ports to USB Type A connectors on front panel

SATA

- Two SATA ports to mSATA connector
- Two SATA ports to internal SATA connectors

Dataplane Breakout

- One dataplane breakout site
- Two 10GBASE-T Ethernet ports to RJ-45 connectors via XIt3000 breakout module (optional)
- x4 PCIe Gen2 via Molex iPASS™ connector

XIM Support

- One XIM site
- X12d support

Physical Characteristics

- 3U VPX Rear Transition Module (RTM)

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1
- Conformal coating available as an ordering option

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g ² /Hz (maximum), 5 to 2000 Hz	0.04 g ² /Hz (maximum), 5 to 2000 Hz	0.1 g ² /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

